

CP327V-MPSA27 **NPN - Darlington Transistor Die** 0.5 Amp, 60 Volt

The CP327V-MPSA27 die is a silicon NPN Darlington power transistor designed for high gain amplifier applications.

	M	ECHANICAL	SPECIFICAT	IONS:	
		Die Size		22.8 x 22.8 MILS	
		Die Thickness		7.1 MILS	
		Base Bonding Pad Size		4.7 x 4.7 MILS	
		Emitter Bonding Pad Size		4.7 x 4.7 MILS	
		Top Side Metalization		Al-Si – 17,000Å	
		Back Side Metalization		Au – 9,000Å	
		Scribe Alley Width		1.8 MILS	
		Vafer Diamete	er	5 INCHES	
BACKS	IDE COLLECTOR R0	Fross Die Per	Wafer	33,085	
DACKS					
MAXIMUM RATINGS: (T _A =25°C)			SYMBOL		UNITS
Collector-Base Voltage			VCBO	60	V
Collector-Emitter Voltage			VCES	60	V
Emitter-Base Voltage			VEBO	10	V
Continuous Collector Current			IC	0.5	А
Operating and Storage Junction Temperature			T _{J,} T _{stg}	-65 to +150	°C
	L CHARACTERISTICS:	(T _A =25°C un			
SYMBOL			MIN	MAX 100	UNITS nA
I _{CBO}	V _{CB} =50V			500	nA
ICES	V _{CE} =50V				
I _{EBO}	V _{EB} =10V			100	nA
BV _{CBO}	I _C =100μΑ		60		V
BVCES	Ι _C =100μΑ		60		V
V _{CE(SAT)}	I _C =100mA, I _B =0.1mA			1.5	V
V _{BE(ON)}	V _{CE} =5.0V, I _C =100mA			2.0	V
h _{FE}	V _{CE} =5.0V, I _C =10mA		10K		
h _{FE}	V _{CE} =5.0V, I _C =100mA		10K		

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V_{CE}=5.0V, I_C=10mA, f=100MHz

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MECHANICAL SPECIFICATIONS:

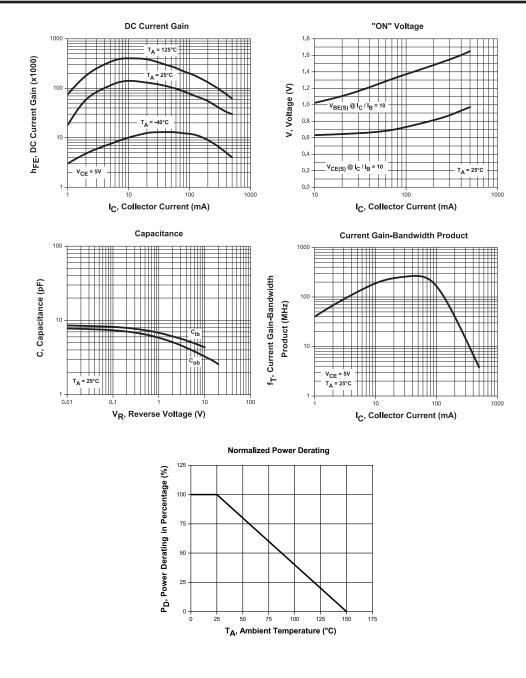
R0 (22-January 2020)

MHz

CP327V-MPSA27 Typical Electrical Characteristics



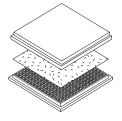
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BARE DIE PACKING OPTIONS



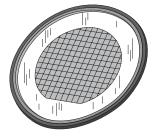


BARE DIE IN TRAY (WAFFLE) PACK

- CT: Singulated die in tray (waffle) pack. (example: CP211-PART NUMBER-CT)
- CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-<u>PART NUMBER</u>-CM)

UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked. (example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

www.centralsemi.com

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- · Consolidated shipping options

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities

Special wafer diffusions

· Custom product packing

- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits

Custom bar coding for shipments

Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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